

Title (en)
METHOD AND DEVICE FOR STRUCTURING PRINTED CIRCUIT BOARDS

Title (de)
VERFAHREN UND EINRICHTUNG ZUR STRUKTURIERUNG VON LEITERPLATTEN

Title (fr)
PROCEDE ET DISPOSITIF POUR STRUCTURER DES CARTES DE CIRCUIT

Publication
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Application
EP 02740352 A 20020515

Priority
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Abstract (en)
[origin: DE10127357C1] The manufacturing equipment incorporates a table (10) carrying a substrate plate (1). There is a control circuit (9) with connections to first and second lasers (11,21) with lenses (12,23). The light from the lasers (14,24) is directed onto small working areas (3,4) on the plate. The control system may regulate movement of the plate in the x and y directions.

IPC 1-7
H05K 3/06

IPC 8 full level
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CPC (source: EP KR US)
H05K 3/027 (2013.01 - EP US); **H05K 3/06** (2013.01 - KR); **H05K 3/062** (2013.01 - EP US); **H05K 1/0263** (2013.01 - EP US); **H05K 1/0265** (2013.01 - EP US); **H05K 3/4644** (2013.01 - EP US); **H05K 2201/09727** (2013.01 - EP US); **H05K 2203/108** (2013.01 - EP US)

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